

Docket No.: A8319.0014/P014
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Takeyuki Itabashi, et al.

Application No.: Not Yet Assigned

Group Art Unit: N/A

Filed: Herewith

Examiner: Not Yet Assigned

For: ELECTROLESS COPPER PLATING
SOLUTION, ELECTROLESS COPPER
PLATING PROCESS AND PRODUCTION
PROCESS OF CIRCUIT BOARD



CLAIM FOR PRIORITY

Commissioner for Patents
Washington, DC 20231

Dear Sir:

Applicant hereby claims priority under 35 U.S.C. 119 based on the following
prior foreign application filed in the following foreign country on the date indicated:

<u>Country</u>	<u>Application No.</u>	<u>Date</u>
Japan	2001-048685	February 23, 2001

In support of this claim, a certified copy of the said original foreign application will be filed shortly.

Dated: February 19, 2002

Respectfully submitted,

By 

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